fischer elektronik 23

Heatsinks for DIL-IC, PLCC and SMD

Heatsinks for PLCC

art. no.	R _{th} [K/W]	₫ [mm]
ICK R	19	12
art. no.	R _{th} [K/W]	 ↔ [mm]
ICK PLCC 28	25	11.8
art. no.	R _{th} [K/W]	 ↔ [mm]
ICK CC 64	17	17

surface: black anodised

Unsupported thermal conductive film \rightarrow E 13 Thermal conductive glue \rightarrow E 14

 Thermal conductive glue
 → E 14

 Heatsinks for PLCC
 → B 24

 Thermal. conductive silicone foam foil→ E 6

Thermal conductive paste

Thermal conduct. foil WLFT 404/405 → E 5

Mounting material for semiconduct. \rightarrow E 34 – 38

 \rightarrow E 12

→ E 39 – 40

B

C

D

G

Н

Κ

Ν

B 24